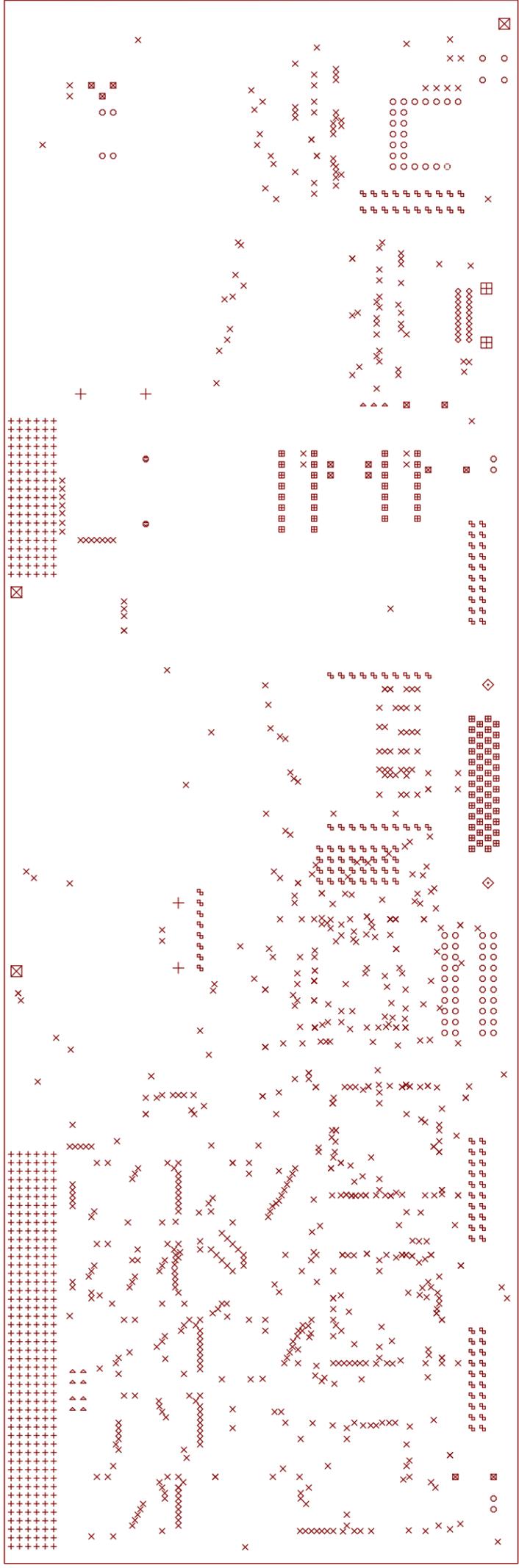


Chamfer 2 places 0.060 X 45 degrees Mill edge of PCB on SolderSide



Chamfer 2 places 0.060 X 45 degrees Mill edge of PCB on SolderSide

DRILL DRAWING

HOLE LEGEND				
SYM	DIAM	TOL	QTY	NOTE
x	0.012		738	
+	0.025		396	
o	0.027		20	
■	0.031		13	
▣	0.034		80	
⊞	0.037		140	
o	0.038		75	
△	0.042		11	
●	0.050		2	
+	0.057		4	
◇	0.109		2	
⊠	0.110		3	
⊞	0.116		2	
TOTAL			1486	

Gerber File Name Board Layer Stacking Order
 demrev2a.top Top Layer 1 = Top Layer
 demrev2a.in1 Inner Layer 2 = Inner Trace 1
 demrev2a.pwr Inner Layer 3 = Power Plane
 demrev2a.in2 Inner Layer 4 = Inner Trace 2
 demrev2a.in3 Inner Layer 5 = Inner Trace 3
 demrev2a.gnd Inner Layer 6 = Ground Plane
 demrev2a.in4 Inner Layer 7 = Inner Trace 4
 demrev2a.bot Bottom Layer 8 = Bottom Layer

Overall PC board thickness = 0.093 +/- 0.008 Inch
 Mill PC board edge to a thickness of 0.063 +/- 0.008 inch on SolderSide for a distance of 0.098 inch from the top and bottom of the board
 Chamfer front 2 corners of board 0.060 x 45 degrees

Sept. 9, 1998